

UÄur BÃ¼yÃ¼k

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Effect of Heat Treatment on the Microstructures and Mechanical Properties of Al-4Cu-1.5Mg Alloy. International Journal of Metalcasting, 2022, 16, 1020-1033.	1.9	5
2	Subtle nuances in personality differences between gifted children as perceived by parents and teachers. Gifted Education International, 2021, 37, 305-320.	1.8	0
3	EFFECT OF CU CONTENT AND GROWTH VELOCITY ON THE MICROSTRUCTURE PROPERTIES OF THE DIRECTIONALLY SOLIDIFIED AL-MN-CU TERNARY ALLOYS. EJONS International Journal of Mathematic Engineering and Natural Sciences, 2021, 5, 756-764.	0.0	0
4	Directionally Solidified Al-Cu-Si-Fe Quaternary Eutectic Alloys. Physics of Metals and Metallography, 2020, 121, 78-83.	1.0	6
5	Effect of growth velocity on microstructure and mechanical properties of directionally solidified 7075 alloy. International Journal of Cast Metals Research, 2020, 33, 11-23.	1.0	7
6	Effect of Robotics Technology in Science Education on Scientific Creativity and Attitude Development. Journal of Turkish Science Education, 2020, 18, 54-72.	0.7	1
7	Investigation of the thermo-electrical properties of A707 alloys. Thermochimica Acta, 2019, 673, 177-184.	2.7	3
8	Microstructural, mechanical, electrical, and thermal properties of the Bi-Sn-Ag ternary eutectic alloy. Journal Wuhan University of Technology, Materials Science Edition, 2017, 32, 147-154.	1.0	3
9	Effect of silicon content on microstructure, mechanical and electrical properties of the directionally solidified Al-based quaternary alloys. Journal of Alloys and Compounds, 2017, 694, 471-479.	5.5	32
10	The effects of microstructure and growth rate on microhardness, tensile strength, and electrical resistivity for directionally solidified Al-Ni-Fe alloys. Journal of Alloys and Compounds, 2016, 660, 23-31.	5.5	44
11	Solidification Behavior of Ge-Al Eutectic Alloy in a Drop Tube. Transactions of the Indian Institute of Metals, 2016, 69, 961-970.	1.5	5
12	Characterization of Rapidly Solidified Nd-Al and Nd-Ag Eutectic Alloys in Drop Tube. Advanced Engineering Materials, 2015, 17, 359-365.	3.5	1
13	Directional solidification of Zn-Al-Cu eutectic alloy by the vertical Bridgman method. Journal of Mining and Metallurgy, Section B: Metallurgy, 2015, 51, 67-72.	0.8	7
14	The influence of the growth rate on the eutectic spacings, undercoolings and microhardness of directional solidified bismuth-lead eutectic alloy. Current Applied Physics, 2013, 13, 587-593.	2.4	9
15	Containerless solidification of Ag-Al and Ag-Cu eutectic alloys in a drop tube. Journal of Alloys and Compounds, 2013, 575, 96-103.	5.5	11
16	Variations of microhardness with solidification parameters and electrical resistivity with temperature for Al-Cu-Ag eutectic alloy. Current Applied Physics, 2012, 12, 7-10.	2.4	25
17	Determination of mechanical, electrical and thermal properties of the Sn-Bi-Zn ternary alloy. Journal of Non-Crystalline Solids, 2011, 357, 2876-2881.	3.1	33
18	Microstructural characterization of unidirectional solidified eutectic Al-Si-Ni alloy. Materials Characterization, 2011, 62, 844-851.	4.4	35

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19	Determination of solid-liquid interfacial energy for a solid Sn in equilibrium with a Sn-Ag-Zn eutectic liquid. <i>Current Applied Physics</i> , 2011, 11, 1060-1066.	2.4	9
20	Dependence of Electrical Resistivity on Temperature and Sn Content in Pb-Sn Solders. <i>Journal of Electronic Materials</i> , 2011, 40, 195-200.	2.2	22
21	Measurements of Microhardness and Thermal and Electrical Properties of the Binary Zn-0.7wt.%Cu Hypoperitectic Alloy. <i>Journal of Electronic Materials</i> , 2010, 39, 303-311.	2.2	17
22	Investigation of microhardness and thermo-electrical properties in the Sn-Cu hypereutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 468-474.	2.2	13
23	Investigation of the effect of solidification processing parameters on the rod spacings and variation of microhardness with the rod spacing in the Sn-Cu hypereutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 608-618.	2.2	15
24	Effect of solidification parameters on the microstructure of Sn-3.7Ag-0.9Zn solder. <i>Materials Characterization</i> , 2010, 61, 1260-1267.	4.4	21
25	Dependency of eutectic spacings and microhardness on the temperature gradient for directionally solidified Sn-Ag-Cu lead-free solder. <i>Materials Chemistry and Physics</i> , 2010, 119, 442-448.	4.0	36
26	Dependency of the thermal and electrical conductivity on the temperature and composition of Cu in the Al based Al-Cu alloys. <i>Experimental Thermal and Fluid Science</i> , 2010, 34, 1507-1516.	2.7	62
27	Investigation of the effect of solidification processing parameters on microhardness and determination of thermo-physical properties in the Zn-Cu peritectic alloy. <i>Journal of Alloys and Compounds</i> , 2010, 491, 143-148.	5.5	15
28	DETERMINATION OF ANISOTROPY OF CRYSTAL-MELT INTERFACIAL ENERGY FROM THE OBSERVED GRAIN BOUNDARY GROOVE SHAPES AT MULTIPLE ORIENTATIONS. <i>Surface Review and Letters</i> , 2009, 16, 579-588.	1.1	0
29	MEASUREMENTS OF SOLID-LIQUID INTERFACIAL ENERGIES IN THE ORGANIC MONOTECTIC ALLOYS. <i>Surface Review and Letters</i> , 2009, 16, 203-214.	1.1	3
30	Directional solidification of Al-Cu-Ag alloy. <i>Applied Physics A: Materials Science and Processing</i> , 2009, 95, 923-932.	2.3	59
31	Interfacial energies of carbon tetrabromide. <i>Current Applied Physics</i> , 2009, 9, 359-366.	2.4	3
32	Unidirectional solidification of Zn-rich Zn-Cu hypoperitectic alloy. <i>Journal of Materials Research</i> , 2009, 24, 3422-3431.	2.6	14
33	Investigation of directional solidified Al-Ti alloy. <i>Journal of Non-Crystalline Solids</i> , 2009, 355, 1231-1239.	3.1	5
34	The effect of growth rate on microstructure and microindentation hardness in the In-Bi-Sn ternary alloy at low melting point. <i>Journal of Alloys and Compounds</i> , 2009, 470, 150-156.	5.5	43
35	Novel experimental technique to observe equilibrated grain boundary groove shapes in opaque alloys. <i>Journal of Alloys and Compounds</i> , 2009, 476, 213-219.	5.5	21
36	The microstructure parameters and microhardness of directionally solidified Sn-Ag-Cu eutectic alloy. <i>Journal of Alloys and Compounds</i> , 2009, 485, 264-269.	5.5	43

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37	Experimental investigation of the effect of solidification processing parameters on the rod spacings in the Sn-1.2wt.% Cu alloy. <i>Journal of Alloys and Compounds</i> , 2009, 486, 199-206.	5.5	44
38	Determination of interfacial energies in the Al-Ag and Sn-Ag alloys by using Bridgman type solidification apparatus. <i>Journal of Alloys and Compounds</i> , 2009, 488, 138-143.	5.5	22
39	Variation of microindentation hardness with solidification and microstructure parameters in the Al based alloys. <i>Applied Surface Science</i> , 2008, 255, 3071-3078.	6.1	62
40	Investigation of liquid composition effect on Gibbs-Thomson coefficient and solid-liquid interfacial energy in SCN based binary alloys. <i>Materials Characterization</i> , 2008, 59, 998-1006.	4.4	23
41	Interfacial energy of solid In ₂ Bi intermetallic phase in equilibrium with In-Bi eutectic liquid at 72°C equilibrating temperature. <i>Materials Characterization</i> , 2008, 59, 1101-1110.	4.4	20
42	Solid-liquid interfacial energy of dichlorobenzene. <i>Journal of Physics Condensed Matter</i> , 2007, 19, 116202.	1.8	25
43	Measurement of solid-liquid interfacial energy in the In-Bi eutectic alloy at low melting temperature. <i>Journal of Physics Condensed Matter</i> , 2007, 19, 506102.	1.8	16
44	Interfacial energies of p-dichlorobenzene-succinonitrile alloy. <i>Thermochimica Acta</i> , 2007, 463, 44-52.	2.7	11
45	Solid-liquid interfacial energy for solid succinonitrile in equilibrium with succinonitrile dichlorobenzene eutectic liquid. <i>Thermochimica Acta</i> , 2006, 445, 86-91.	2.7	25
46	Measurement of solid-liquid interfacial energy in the pyrene succinonitrile monotectic system. <i>Journal of Physics Condensed Matter</i> , 2006, 18, 8403-8412.	1.8	22
47	Solid-liquid interfacial energy of pyrene. <i>Journal of Applied Physics</i> , 2006, 100, 123505.	2.5	28
48	Measurement of solid-liquid interfacial energy in succinonitrile-pyrene eutectic system. <i>Materials Letters</i> , 2005, 59, 2953-2958.	2.6	27
49	The Effect of Growth Rate on the Microstructure and Mechanical Properties of 7020 Alloys. <i>Journal of Materials Engineering and Performance</i> , 0, , 1.	2.5	1